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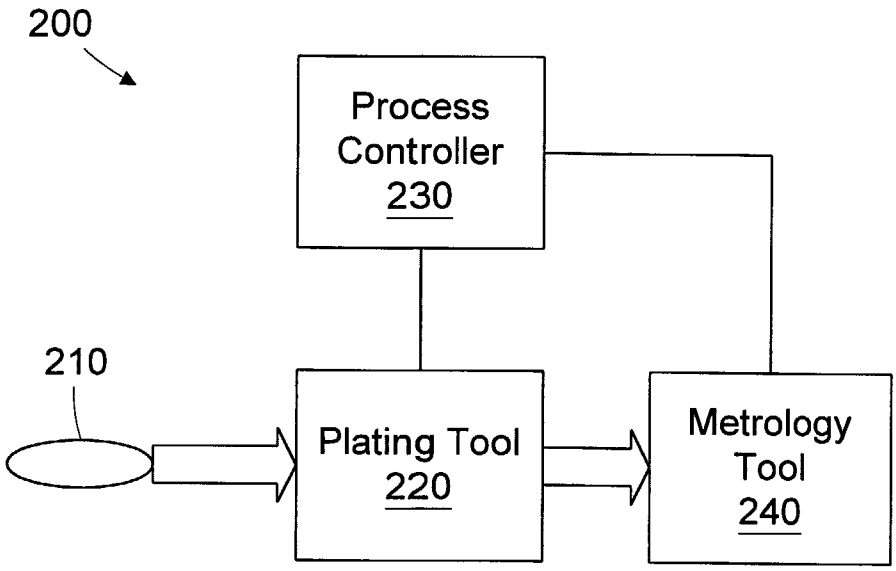
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(54) Title: METHOD AND APPARATUS FOR CONTROLLING A PLATING PROCESS



(57) Abstract: A method for a controlling a plating process layer (160) on a wafer in accordance with a recipe; measuring a thickness of the process layer (160); and determining at least one plating parameter of the recipe for subsequently formed process layers (160) based on the measured thickness. A processing line (200) includes a plating tool (220), a metrology tool (240), and a process controller (230). The plating tool (220) is adapted to form a process layer (160) on a wafer in accordance with a repice. The metrology tool (240) is adapted to measure a thickness of the process layer (160). The process controller (230) is adapted to determine at least one plating parameter of the recipe for subsequently formed process layers (160) based on the measured thickness.

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